CLAIMS

[1] A sheet for use in electronic component packaging, comprising (A) 29 to 65 parts by mass of a styrene-conjugated diene block copolymer; (B) 51 to 15 parts by mass of a polystyrene resin; and (C) 20 to 9 parts by mass of a high-impact polystyrene resin; wherein the components (A) to (C) have weight-average molecular weights (Mw) in the following ranges:

component (A): Mw = 80,000 to 220,000;

component (B): Mw = 200,000 to 400,000;

component (C): Mw = 150,000 to 210,000.

[2] The sheet for use in electronic component packaging according to claim 1, having a melt tension at 200 °C of 10 to 30 mN.

[3] The sheet for use in electronic component packaging according to claim 1 or claim 2, wherein the proportion of the conjugated diene blocks in 100 mass% of component (A) is 10 to 25 mass%.

[4] The sheet for use in electronic component packaging according to any one of claims 1 to 3, wherein the peak molecular weight of the styrene blocks of component (A) as measured by GPC is in the range of 30,000 to 120,000, and the half-width of the molecular weight distribution curve of the styrene blocks is in the range of 0.8 to 1.25.

[5] The sheet for use in electronic component packaging according to any one of claims 1 to 4, wherein the particle size of the graft rubber in component (C) is 2.0 to 3.0 μm, and the proportion of rubber in the graft rubber of the substrate is 0.75 to 1.90 mass%.

[6] An embossed carrier tape using the sheet according to any one of claims 1 to 5.

CLAIMS:

1. A sheet for use in electronic component packaging, comprising (A) 29 to 65 parts by mass of a styrene-conjugated diene block copolymer comprising at least one styrene block and at least one conjugated diene block; (B) 51 to 15 parts by mass of a polystyrene resin; and (C) 20 to 9 parts by mass of a high-impact polystyrene resin comprising graft rubber particles; wherein the components (A) to (C) have weight-average molecular weights (Mw) in the following ranges:

component (A): Mw=140,000 to 220,000;

component (B): Mw=200,000 to 400,000;

component (C): Mw=150,000 to 190,000,

wherein the average particle size of the graft rubber particles in component (C) is 2.0 to 3.0 μm, and the proportion of the graft rubber particles in the sheet is 0.75 to 1.90 mass %, the sheet being 100 mass %.

2. The sheet for use in electronic component packaging according to claim 1, having a melt tension at 200°C. of 10 to 30 mN.

3. The sheet for use in electronic component packaging according to claim 1, wherein the proportion of the at least one conjugated diene block in 100 mass % of component (A) is 10 to 25 mass %.

4. The sheet for use in electronic component packaging according to claim 1, wherein the peak molecular weight of the at least one styrene block of component (A) as measured by GPC is in the range of 30,000 to 120,000, and the half-width of the molecular weight distribution curve of the at least one styrene block is in the range of 0.8 to 1.25.

5. An embossed carrier tape comprised of the sheet according to claim 1.